



CONDUCTOR FOR FORMING CONDUCTIVE PATH ON AN INTEGRATED
CIRCUIT AND METHOD

ABSTRACT

A conductor (80) for the repair of, or addition to, a circuit includes a conductive element (46) and at least one of a diffusion barrier (52) or bonding medium (54) adjacent to a conductive element surface (48, 50).

The diffusion barrier inhibits the diffusion of the material from which the conductive element is made into a bonding tip used to effect bonding of the conductor to the circuit.

The bonding medium enhances bonding between the conductive element and the circuit.

Figure 5